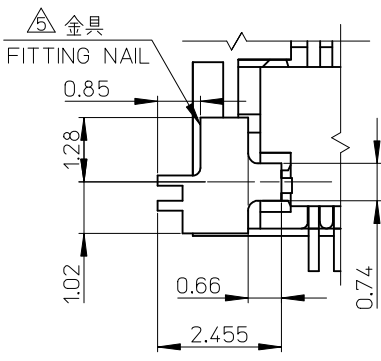
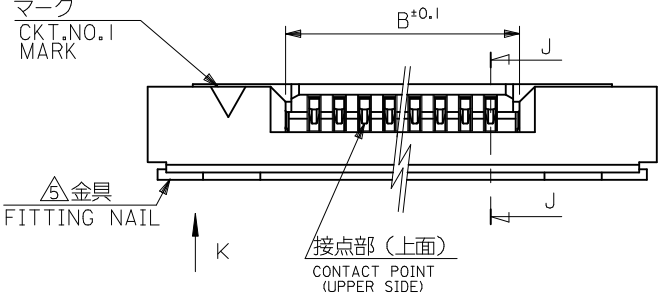
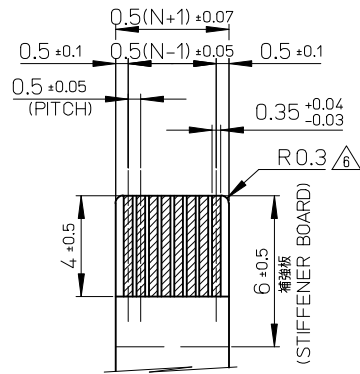


16.1	14.3	10.65	9.5	52745-2090	20
15.6	13.8	10.15	9	52745-1990	19
15.1	13.3	9.65	8.5	52745-1890	18
14.1	12.3	8.65	7.5	52745-1690	16
13.6	11.8	8.15	7	52745-1590	15
12.6	10.8	7.15	6	52745-1390	13
11.6	9.8	6.15	5	52745-1190	11
11.1	9.3	5.65	4.5	52745-1090	10
10.6	8.8	5.15	4	52745-0990	9
10.1	8.3	4.65	3.5	52745-0890	8
9.6	7.8	4.15	3	52745-0790	7
9.1	7.3	3.65	2.5	52745-0690	6
8.1	6.3	2.65	1.5	52745-0490	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

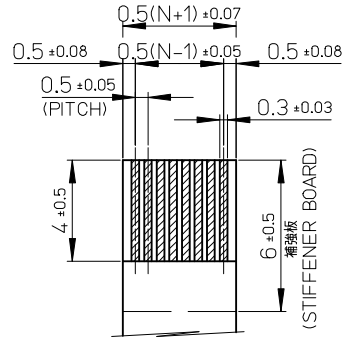


CONNECTOR SERIES NO. : 52745-\*\*17

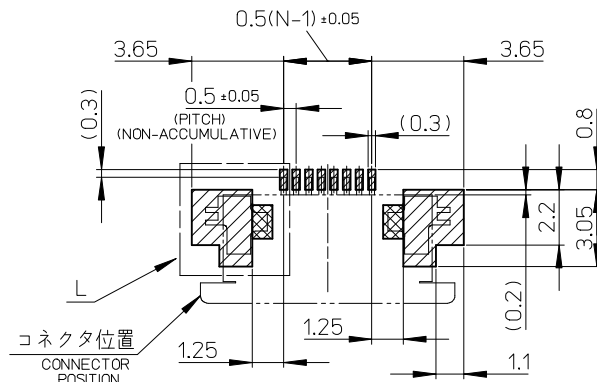
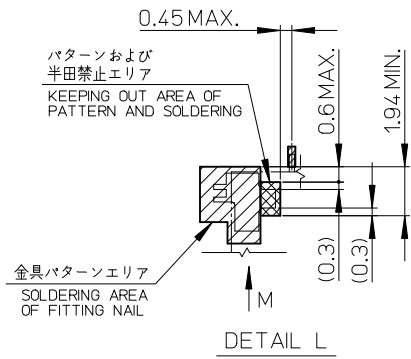
REVISED EC NO: J2015-0016 DRWN: THIRAYAMA 2014/07/09 CHKD: YKOBAYASHI 022014/07/09 APPR: YNOGAWA 2014/07/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE <b>10:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION
	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3	DRAWN BY SAIHARA DATE 1994/03/24	TITLE <b>0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING</b>				
	ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	CHECKED BY SKUNISHI DATE 2000/06/30	MATERIAL NO. <b>SEE CHART</b>				
		APPROVED BY KMORIKAWA DATE 2010/07/16	DOCUMENT NO. <b>SD-52745-054</b>				
J	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				SHEET NO. 1 OF 2		



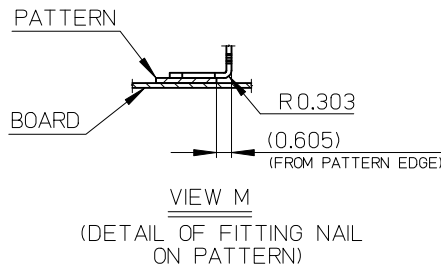
適合金めっきFPC推奨寸法  
 APPLICABLE FPC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.03  
 THICKNESS: 0.3±0.03/-0.03



適合金めっきFFC推奨寸法  
 APPLICABLE FFC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.03  
 THICKNESS: 0.3±0.03/-0.03



参考基板レイアウト  
 (マウント面)  
 RECOMMENDED P.C BOARD  
 PATTERN DIMENSION(REF.)  
 (MOUNTING SIDE)



注記NOTES

1. 使用材料  
 MATERIAL  
 ハウジング: 46ナイロン、ガラス充填、UL94V-0、白  
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE  
 アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒  
 ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK  
 ターミナル: リン青銅、銅下地半田めっき (t=0.2)  
 TERMINAL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING  
 金具: リン青銅、銅下地半田めっき (t=0.2)  
 FITTING NAIL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING
2. エンボステープ梱包時は、アクチュエータがロックした状態になります。  
 IN THE PACKAGE, ACTUATOR OF PART NO.52745-\*\*17 SHOULD BE LOCKED.
3. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H.  
 UPPER DIRECTION: 0.1MAXIMUM  
 LOWER DIRECTION: 0.15 MAXIMUM
4. 偶数極に適用  
 APPLY FOR EVEN CIRCUIT.
5. ハ' ターン剥離止め金具  
 FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.
6. R0.3は、FPCの胴体部にかからないこと  
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

FPCについて:

打抜き方向は導体側から補強板を推奨致します。  
 補強フィルム材質はポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。  
 ABOUT FPC:  
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

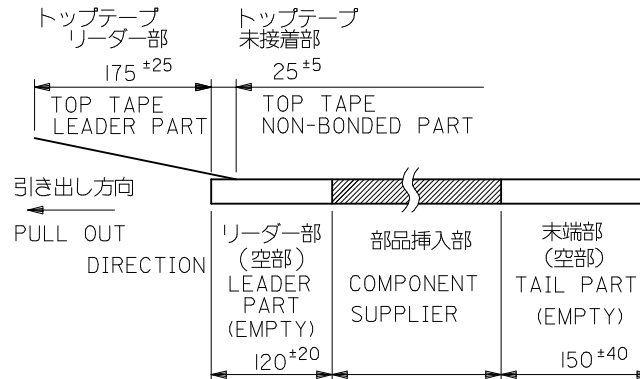
REVISED EC NO: J2015-0016 DRWN: THIRAYAMA 2014/07/09 CHKD: YKOBAYASHI 022014/07/09 APPR: YNOGAWA 2014/07/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY SAIHARA	DATE 1994/03/24	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING <b>molex</b> DOCUMENT NO. SD-52745-054 SHEET NO. 2 OF 2		
	10 OVER 30 UNDER	± ---	CHECKED BY SKUNISHI	DATE 2000/06/30			
	30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2010/07/16			
ANGULAR ±3 °		MATERIAL NO. SEE SHEET 1 OF 2					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

注記 NOTES

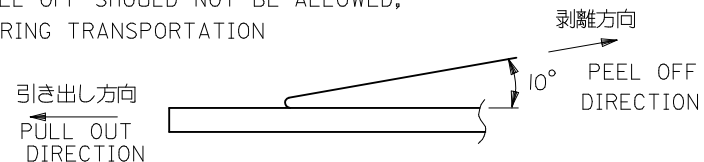
1. 製品番号 52745-\*\*17 の梱包状態はアクチュエータがロックした状態とする。  
 詳細寸法については図面 SD-52745-054 を参照下さい。  
 IN THE PACKAGE,ACTUATOR OF PART NO.52745-\*\*17 SHOULD BE LOCKED  
 RE DETAILED DIMENSIONS,SEE SD-52745-054

2. 梱包数量：1000個/リール  
 NUMBER OF CONNECTORS:1000PCS/REEL

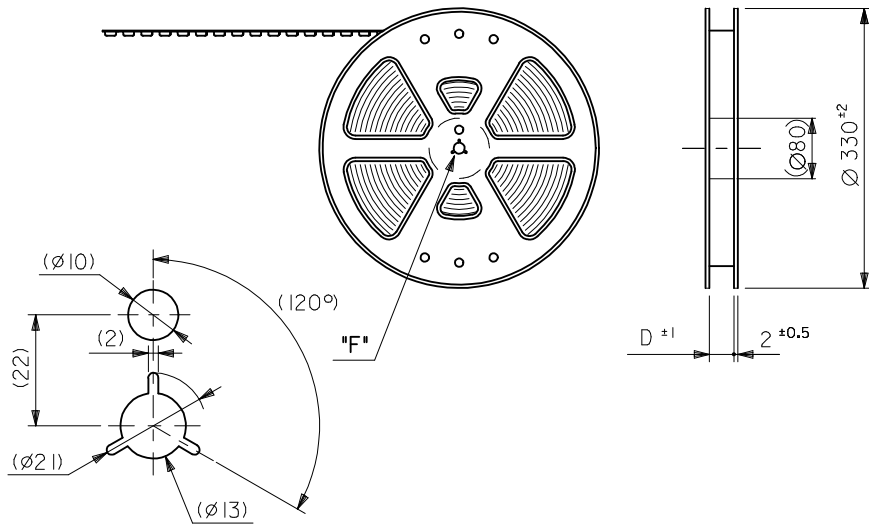
3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度：(剥離方向は下図参照)  
 0.1N~0.7N(10.2gf~71.4gf) 尚、本規格値は、出荷時に適用。  
 (但し、輸送時に剥離が発生しない事。)  
 PEELING OFF FORCE OF TOP TAPE  
 0.1N~0.7N(10.2gf~71.4gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
 PEEL OFF SHOULD NOT BE ALLOWED,  
 DURING TRANSPORTATION



引き出し方向  
 PULL OUT  
 DIRECTION

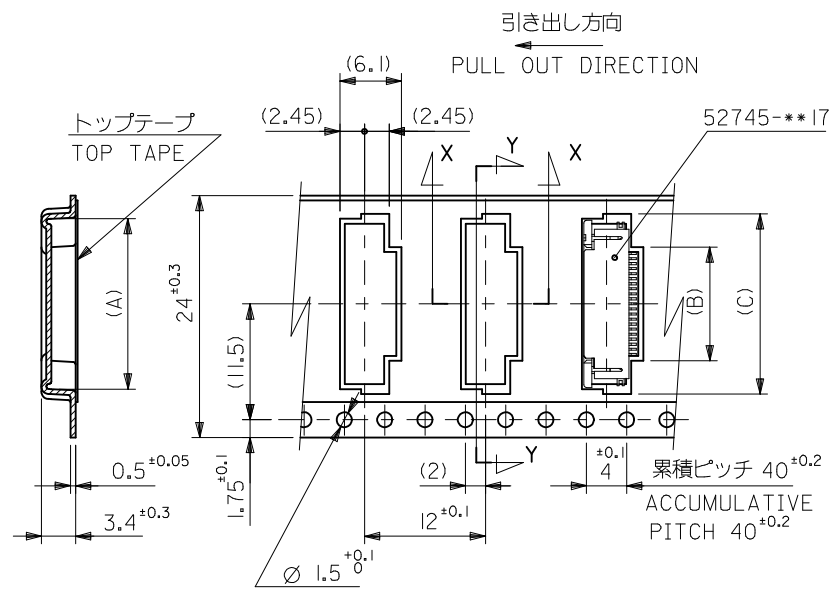


DETAIL "F"

5. 材料 キャリアテープ：ポリプロピレン (PP)  
 トップテープ：PET, PE, PEF  
 リール：ポリスチレン (PS) <リサイクル材を含む>

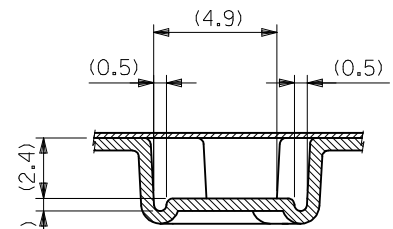
MATERIAL CARRIER TAPE:POLYPROPYLENE  
 TOP TAPE:PET,PE,PEF  
 REEL:POLYSTYREN(PS)  
 <RECYCLE MATERIAL CONTAINED>

REVISED EC NO: J2015-0016 DRWN:THIRAYAMA 2014/07/10 CHKD:YKOBAYASHI 02/2014/07/10 APPR:YNOGAWA 2014/07/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±---	DRAWN BY MTAKAHASHI	DATE 04 2013/07/30	TITLE 0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (1/3)		
	10 OVER 30 UNDER	±---	CHECKED BY KTAKAHASHI	DATE 2013/07/30			
	30 OVER	±---	APPROVED BY YNOGAWA	DATE 2013/11/07			
ANGULAR	±---°	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-52745-057	SHEET NO. 1 OF 3		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



SECT.Y-Y

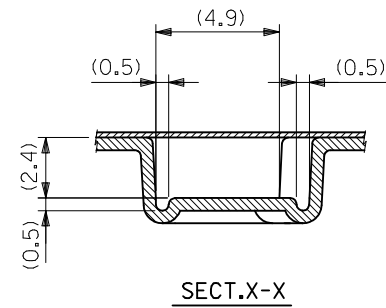
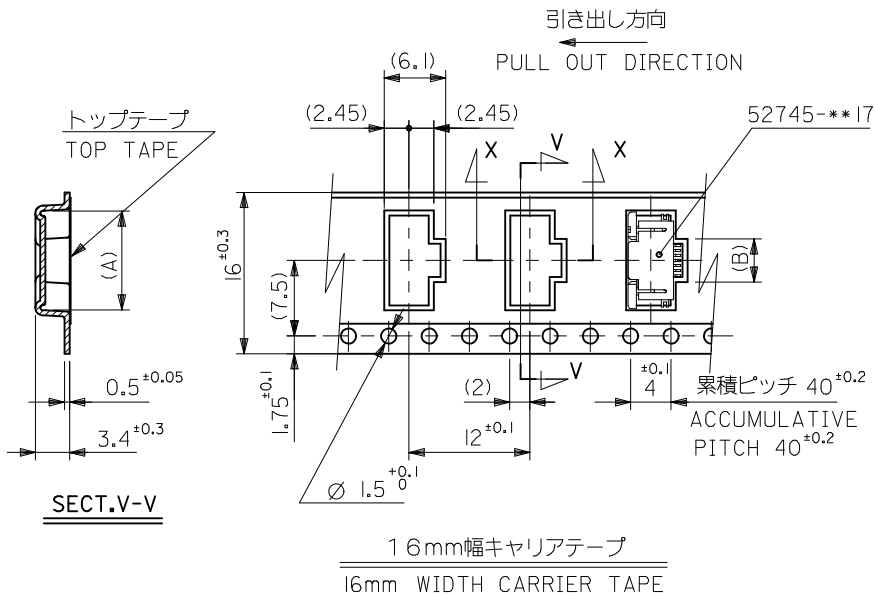
24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE



SECT.X-X

24	25.5	17.4	10.8	16.4	52745-2090	20
		16.9	10.3	15.9	-1990	19
		16.4	9.8	15.4	-1890	18
		15.4	8.8	14.4	-1690	16
		14.9	8.3	13.9	-1590	15
		13.9	7.3	12.9	-1390	13
		12.9	6.3	11.9	-1190	11
		12.4	5.8	11.4	-1090	10
		11.9	5.3	10.9	-0990	9
		11.4	4.8	10.4	-0890	8
10.9	4.3	9.9	-0790	7		
10.4	3.8	9.4	52745-0690	6		
キャリアテープ幅 CARRIER TAPE IDTH	D	(C)	(B)	(A)	ENG. NO.	極数 CIRCUIT

REVISED EC NO: J2015-0016 DRWN: THIRAYAMA 2014/07/10 CHKD: YKOBAYASHI 022014/07/10 APPR: YNOGAWA 2014/07/17	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER ± --- 10 OVER 30 UNDER ± --- 30 OVER ± --- ANGULAR ± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY DATE MTAKAHASHI 04 2013/07/30 CHECKED BY DATE KTAKAHASHI 2013/07/30 APPROVED BY DATE YNOGAWA 2013/11/07	TITLE 0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (2/3)		
	SEE CHART		DOCUMENT NO. SD-52745-057		SHEET NO. 2 OF 3	
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



16	17.5	2.8	8.4	52745-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH	D	(B)	(A)	ENG. NO.	極数 CIRCUIT

REVISED EC NO: J2015-0016 DRWN: THIRAYAMA 2014/07/10 CHKD: YKOBAYASHI 2014/07/10 APPR: YNOGAWA 2014/07/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	---	METRIC	
	DESCRIPTION	10 UNDER	±---	DRAWN BY	DATE	TITLE
		10 OVER 30 UNDER	±---	MTAKAHASHI	2013/07/30	0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (3/3)
	30 OVER	±---	CHECKED BY	DATE		
	ANGULAR	±---°	KTAKAHASHI	2013/07/30		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE		
			YNOGAWA	2013/11/07		
			MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
			SEE CHART	SD-52745-057	3 OF 3	
			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			A3			